Department of Commerce
Ministry of Commerce and Industry,
Government of India

Packaging for Better Living

60 YEARS
DIAMOND JUBILEE
1966 - 2026

भारतीय पैकेजिंग संस्थान
Indian Institute of Packaging

INTERNATIONAL SUMMIT FOR PACKAGING INDUSTRY
ISPI™
2027

7th INTERNATIONAL SUMMIT FOR PACKAGING INDUSTRY

Theme : Global Collaboration , innovation and Sustainability



5th - 6th
February, 2027

Bharat Mandapam,
New Delhi

Organized by
The Indian Institute of Packaging (IIP)

Welcome Message



SHRI R. K. MISHRA, IRS
Director, IIP

I am pleased to introduce the **7th International Summit for Packaging Industry (ISPI 2027)**, **organised by the Indian Institute of Packaging (IIP)**. The theme, the **5S-Ai of Packaging-Safe, Secure, Standardized, Smart, Sustainable and Artificial Intelligent Packaging**, is highly relevant as packaging must protect products while also safeguarding the environment and consumer health.

ISPI 2027 will provide a platform to share knowledge, discuss emerging technologies and network with experts from India and abroad. I am confident it will be a valuable and meaningful forum for the packaging sector.

PROF. (DR.) TANWEER ALAM
Addl. Director & RO, IIP – Delhi,
In-charge, IIP – Lucknow,
Convener, ISPI 2027



It gives me great pleasure to announce the **7th International Summit for Packaging Industry (ISPI 2027)**, **organised by IIP**, scheduled for **5-6 February 2027** at **Bharat Mandapam, New Delhi**.

ISPI 2027 will bring together industry leaders, researchers and professionals from India and overseas to exchange knowledge and explore opportunities across the packaging value chain. The theme, **"The 5S-Ai of Packaging: Safe, Secure, Standardized, Smart, Sustainable and Artificial Intelligent Packaging,"** underscores packaging's role in product protection, sustainablity and innovation.

I look forward to welcoming you to **ISPI 2027** and invite your active participation in making the summit a success.



A GLOBAL PLATFORM FOR **PACKAGING INNOVATION**

The **7th International Summit for Packaging Industry (ISPI 2027)** is a platform for the packaging ecosystem to examine emerging materials, technologies, standards and applications. Organised by the Indian Institute of Packaging, the summit will bring together stakeholders from industry, research, academia and allied sectors.

The summit will focus on the latest trends in packaging materials, conversion technologies and packaging machinery, including automation. Its objectives include improving productivity, reducing wastage and responding to the evolving requirements of packaging user industries and modern consumers.

Theme: Packaging 5S-Ai

Safe, Secure, Standardized, Smart, Sustainable and Artificial Intelligent Packaging.

Concurrent Initiatives

- IIP Packathon – a platform for startups and innovators to present new packaging concepts, materials and solutions.
- Research Conclave – an opportunity for students, scholars and researchers to present packaging-related research and innovation.
- Industry Academia Meet – an avenue to encourage interaction and collaboration between industry and academic institutions.

About the Organiser

The Indian Institute of Packaging (IIP) is an autonomous body established on 14 May 1966 under the Societies Registration Act, 1860, by the Ministry of Commerce & Industry, Government of India, in association with leading packaging and allied industries. IIP works to promote innovative package design and development, provide technical services, upgrade packaging standards, deliver training and develop packaging specifications for domestic and export markets.

KEY FOCUS AREAS



Sustainable & Circular Packaging Materials, design approaches and systems that support reuse, recovery and reduced environmental impact.



AI & Digital Transformation Artificial intelligence, data-led optimisation, predictive quality and digital tools for packaging operations.



Smart & Intelligent Packaging Connected packaging, intelligent labels, sensors and solutions that support product monitoring and consumer engagement.



Advanced Manufacturing & Technologies Packaging machinery, automation, robotics and advanced conversion technologies.



E-commerce & Supply Chain Solutions Packaging solutions for distribution, fulfilment, logistics and product protection.



Policy, Standards & Global Trends Packaging standards, regulatory developments, global compliance and emerging market directions.

Why Attend ISPI 2027?

- Connect with a projected audience of 1,500+ delegates and packaging professionals.
- Hear from 120+ eminent speakers and experts.
- Engage with participants and stakeholders from 25+ countries.
- Explore opportunities to connect with 80+ exhibitors and partners.
- Participate in 10+ knowledge sessions and workshops.
- Build connections across academia, industry and policy.

ABOUT THE **VENUE**



Venue

Bharat Mandapam, Pragati Maidan, New Delhi
Bharat Mandapam is a modern convention and exhibition centre located at Pragati Maidan in New Delhi. It is designed to host large conferences, exhibitions and international events.

Address

Bharat Mandapam (ITPO Complex), Pragati Maidan, New Delhi – 110001, India.
How to Reach

- Nearest Metro Station: Supreme Court Metro Station (Blue Line).
- From IGI Airport: Approximately 25–30 km depending on route; accessible by Airport Express and metro connections or taxi.
- From New Delhi Railway Station: Approximately 3–4 km; around 10–15 minutes by cab or auto, depending on traffic.

REGISTRATION FEE STRUCTURE

CATEGORY	REGISTRATION (till 1st Feb 2027)	ON-SPOT	OVERSEAS
Member of IIP & IIP Alumni	₹12,000	₹15,000	$200
Non-Members	₹15,000	₹18,000	$200
Academic and R&D Institution	₹8,000	₹9,000	$200
Student & Research Scholars	₹7,000	₹8,000	$200

Additional Participation Options

PARTICIPATION TYPE	FEE
One-day participation	₹7,000
Group participation – one day (5 people)	₹35,000
Group participation – two days (5 people)	₹50,000

Note:

- Student Categories: Valid institutional proof/student ID may be required during registration or at the conference.
- Bank charges will be charged additionally and is not included in the Conference fee mentioned

Important:

- Two days participation includes Gala dinner on first day
- Fee includes lunches and Delegate Kit (for conference only).
- For Spot Registrations, Delegate Kit is not guaranteed and is subject to availability.
- An email as Registration Confirmation is sent automatically to the registered email after successful payment.
- Fee mentioned is exclusive of 18% GST.

Cancellation & Refund Policy: Cancellation Request received:

- On or before 31st November 2026: 25% of the registration fee will be deducted
- Between 1st December – 31st December 2026; 50% of the registration fee will be deducted
- Between 1st January and 31st January 2027: 75% of the registration fee will be deducted
- On or after 1st February 2027: No refunds or 100% cancellation will be applicable
- Request must be sent on writing on official email ID. All eligible refunds will be processed after the conference.

Any applicable bank charges and payment gateway fees may be deducted from the refund amount.

CONTACT US

PACKAGING SECRETARIAT

CONVENER / ORGANISING SECRETARY

Prof. (Dr.) Tanweer Alam

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OFFICIAL CONFERENCE MANAGER

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